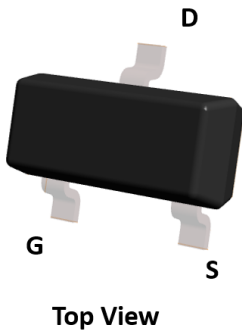
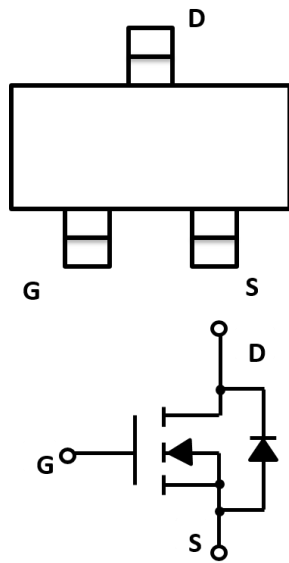


N-Channel Enhancement Mode Field Effect Transistor



SOT-23



Product Summary

- V_{DS} 100V
- I_D 2.0A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) < 310 mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 350 mohm

General Description

- Trench Power MV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- MSL LEVEL1

Applications

- DC-DC Converters
- Power management functions

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	100	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current	I_D	$T_A=25^\circ C$	2.0
		$T_A=70^\circ C$	1.6
Pulsed Drain Current ^A	I_{DM}	8	A
Total Power Dissipation @ $T_A=25^\circ C$	P_D	1.2	W
Thermal Resistance Junction-to-Ambient ^B	$R_{\theta JA}$	105	$^\circ C/W$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ C$

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	100			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS1}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
	I _{GSS2}	V _{GS} = ±10V, V _{DS} =0V			±50	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.1	1.8	3.0	V
Static Drain-Source On-Resistance	R _{Ds(ON)}	V _{GS} = 10V, I _D =2.0A		240	310	mΩ
		V _{GS} = 4.5V, I _D =2.0A		250	350	
Diode Forward Voltage	V _{SD}	I _S =2A, V _{GS} =0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I _S				2.0	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, f=1MHZ		387		pF
Output Capacitance	C _{oss}			31		
Reverse Transfer Capacitance	C _{rss}			28		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =50V, I _D =2.0A		9.56		nC
Gate-Source Charge	Q _{gs}			1.81		
Gate-Drain Charge	Q _{gd}			1.97		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =50V, I _D =1.3A, R _L =39Ω R _{GEN} =1Ω		4		ns
Turn-on Rise Time	t _r			17.8		
Turn-off Delay Time	t _{D(off)}			13.2		
Turn-off fall Time	t _f			28		

A. Pulse Test: Pulse Width ≤300us, Duty cycle ≤2%.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

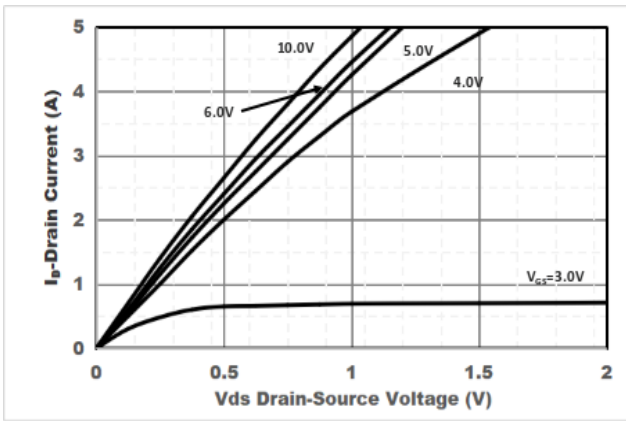


Figure1. Output Characteristics

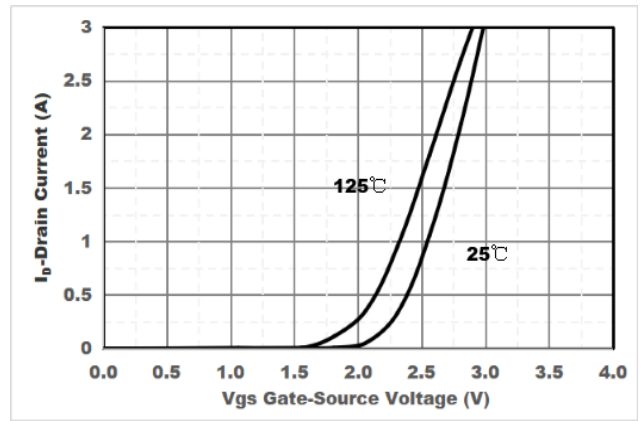


Figure2. Transfer Characteristics

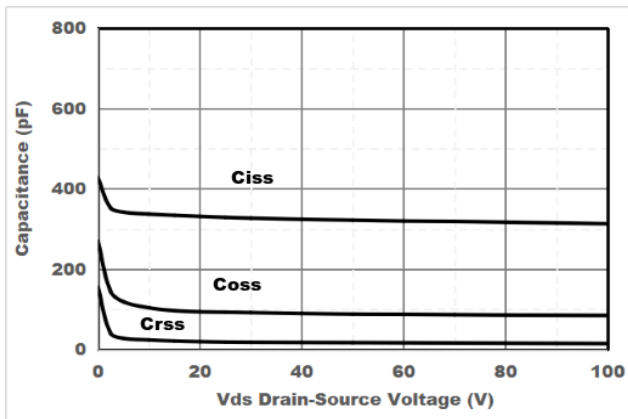


Figure3. Capacitance Characteristics

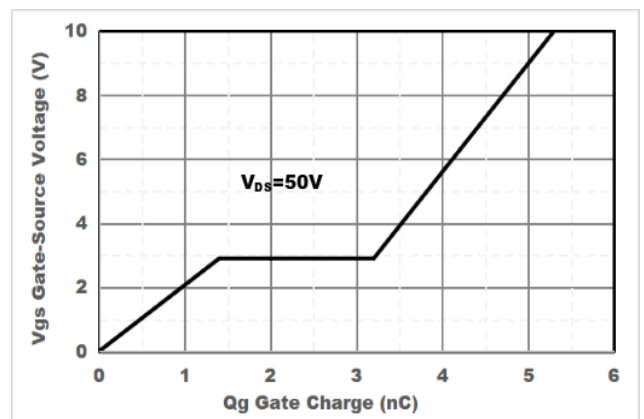


Figure4. Gate Charge

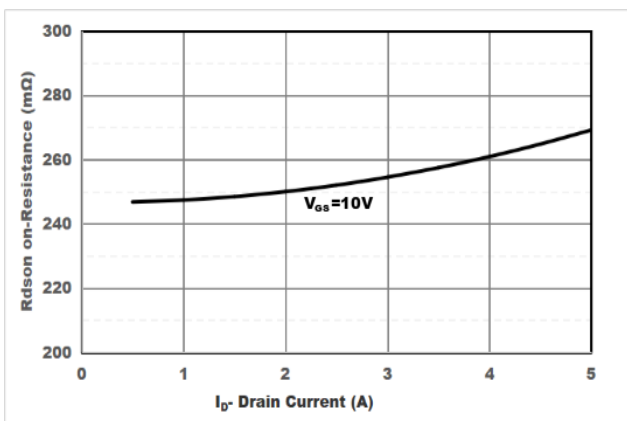


Figure5. Drain-Source on Resistance

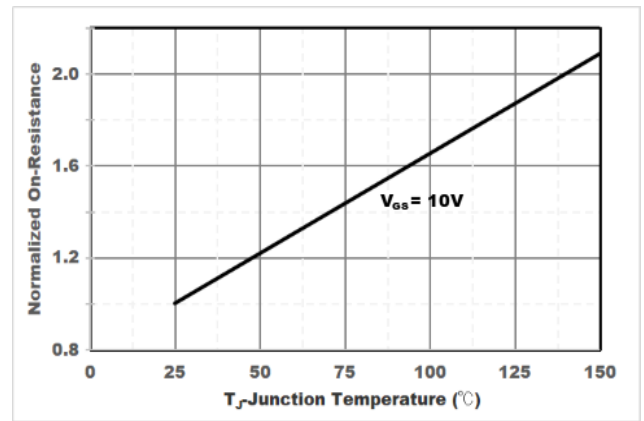


Figure6. Drain-Source on Resistance

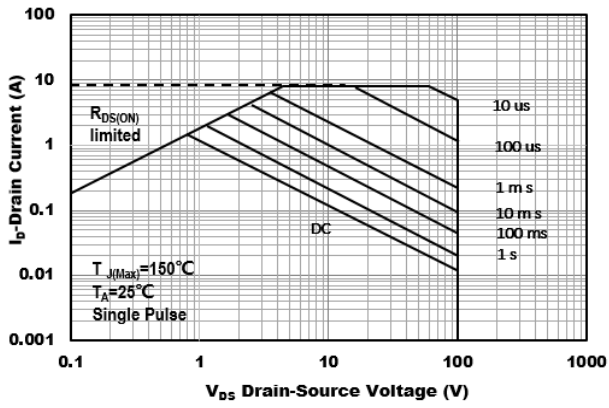


Figure 7. Safe Operation Area

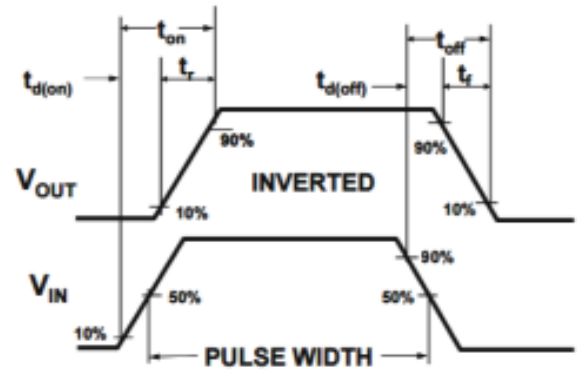
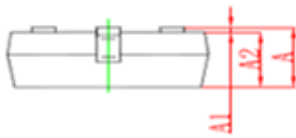
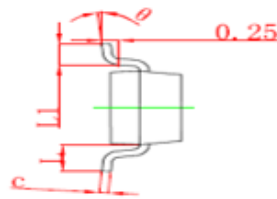
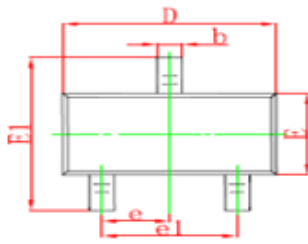


Figure 8. Switching wave

■ SOT-23 Package information



Symbol	Dimensions in Millimeter		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950Type		0.037Type	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.220REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

■ SOT-23 Suggested Pad Layout

